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GA

**INDUSTRY STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GA/T 457-2020

Replacing GA 457-2004

Technical specifications for Resident Identity Card inlays

居民身份证元件层技术规范

(English Translation)

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Foreword

This standard was drafted in accordance with the rules given in GB/T 1.1-2009.

This standard replaces GA 457-2004 "Technical Specification for Resident ID Card Component Layer", and the main changes compared with GA 457-2004 are as follows.

---Revised as a recommended standard;

---Modify the version number of the normative reference documents GB/T 191, GB/T

2828.1, GB/T 6109.4 (see Chapter 2, 2004 edition Chapter 2);

---Modified the technical indicators of enameled copper wire (see 4.1.2, 4.1.2 of the 2004 edition);

---Added the description of the test method judgment result (see Chapter 5, Chapter 5 of the 2004 edition).

Please note that certain contents of this document may involve patents. The publishing organization of this article does not bear the responsibility for identifying these patents.

This standard was proposed by the Public Security Administration of the Ministry of Public Security.

This standard is under the jurisdiction of the Computer and Information Processing Standardization Technical Committee of the Ministry of Public Security.

This standard was drafted. The First Research Institute of the Ministry of Public Security.

1 Scope

This standard specifies the production process requirements and technical requirements, inspection methods and inspection rules for the component layer of the resident ID card.

This standard applies to the component layer of the resident ID card.

2 Normative references

The following documents are indispensable for the application of this document. For dated reference documents, only the dated version applies to this article Pieces. For undated references, the latest version (including all amendments) applies to this document.

GB/T 191-2008 Graphical signs for packaging, storage and transportation GB/T 2828.1-2012 Sampling inspection procedure by attributes Part 1: Batch inspection sampling searched by acceptance quality limit (AQL) plan GB/T 6109.4-2008 Enameled round winding wire Part 4: Direct welding polyurethane enameled round copper wire, class 130 GA/T 449-2013 Resident ID card terms GA/T 460.1-2020 Technical specifications for the body material and printing film of the resident ID card. Part 1: White cushion for card printing PETG film GA/T 460.4-2020 Technical specifications for resident ID card body materials and printing films Part 4: Card-making modules and coil holders Carrier white PETG film ISO/IEC 10373-1:1998 Identification Card Test Method Part 1: General Performance Test

3 Terms and definitions

The following terms and definitions defined in GA/T 449-2013 apply to this document.

Standard test template stardardtestingtemplate Transparent template used to compare the positions of coils and modules in the component layer. Use coordinate lines to draw the standard of component layer, module and coil on the template position.

Responsetesting

Use a special tester to test the continuity between the coil and the module on the component layer.

4.1.1 Module

Comply with relevant requirements for IC packaging technology of resident ID card.

4.1.2 Enameled copper wire

Material. Direct welding polyurethane enameled copper wire.